ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composit © Copyright 2005. IPC, J international and Pan-An	Bannockb	urn, Illinois. A	Il rights reserved untions.	under both	This docum level parts, t	ent is a dec the declara	claration tion enc	n of the substar compasses all le	nces wi ower le	thin the manufactur evel materials for wh	rer listed i hich the n	tem. Not nanufact	te: if the turer has	item is an asso engineering re	embly with lower sponsibility.
1752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg Information					
Supplier Inform	ation															
Company name*			Company unique ID			Unique ID Authority					Response Date*					
onsemi										2025-05-11						
Contact Name			Title - Contact			Phone - Contact*					Email - Contact*					
Product-Env-Stewards			Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com					
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com					
Requester	Requester Item Number Mfr Item		Number Mfr Item Name				Effective	Date	Version	Mai	Manufacturing Site		Weight*	*	UOM	Unit Type
		NCP1612A1DR2G Enhanced, High-Encontroller in SOIC			Efficiency Powe IC10, Vcc 10.5V	er Factor 7, VBUV 1V	2025-05-	5-05-11 PH1			74.7		mg	Each		
Manufacturing I	Proccess Information	I														
Terminal Plating / Grid Array Material Terminal			erminal Base	Base Alloy J-STD-020 MSL Rating			Peak Process Body Temperature Max Time at Peak			Temperature Number of Reflow Cycles						
Matte Tin (Sn) - annealed CU Alloy				1		260		С		30	secon	nds 3				
Comments																
level 1 - maximum tii	me at peak temperature d	luring sol	dering is 10-3	0 seconds												
For more information	n regarding material com	position	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.24	mg	Supplier	Silicon (Si)	7440-21-3		1.24	mg
Die Attach	0.1	mg	Supplier	Silver (Ag)	7440-22-4		0.075	mg
			Supplier	Epoxy resins	129915-35-1		0.025	mg
Lead Frame	15.95	mg	Supplier	Silver (Ag)	7440-22-4		0.335	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0319	mg
			Supplier	Iron (Fe)	7439-89-6		0.3988	mg
			Supplier	Copper (Cu)	7440-50-8		15.1844	mg
Mold Compound-Black	55.41	mg		Epoxy resin	proprietary data		2.7705	mg
			Supplier	Phenolic Resin	Proprietary Data		2.7705	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.1082	mg
			Supplier	Carbon Black (C)	1333-86-4		0.277	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		48.4837	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Au	0.11	mg	Supplier	Gold (Au)	7440-57-5		0.11	mg